



Institute of Electrical and Electronics Engineers, Inc.

Phoenix Section

Components, Packaging, and Manufacturing Technology Society Chapter

And

Waves and Devices Chapter

Present an All Day Workshop on

Emerging Device & Packaging Technologies

APPLICATION TO EXHIBIT

The organization/firm designated below wishes to apply for exhibit space at the **Emerging Device & Packaging Technologies Workshop** at Arizona State University, Tempe, Arizona, on **November 14, 2008**.

Exhibiting Company _____

List of items to be exhibited _____

Company Address _____

	Full Street Address	Suite / Mail Stop	City	State	Zip
CONTACT	<input type="checkbox"/> Mr./ <input type="checkbox"/> Ms _____		Phone _____		
	Address _____ <small>Full Street Address Only - No P.O. Box Address Will Be Accepted</small>		Fax _____		
	City _____		State _____	Zip _____	
	Email _____				

Booth Size	Fee / Booth	# of Booths desired	Preferred Booth locations ¹	Additional exhibitor registrations ²
6' x 8'	\$500			
8' x 10'	\$750			
	\$40	Weekend Storage	Required if materials must be stored over the weekend after the workshop³	

Note 1: Refer to attached vendor booth layout to choose preferred locations. Final layout may change slightly. All effort will be made to insure actual location is close to preferred location. Booths will be allotted on a "first-pay, first-allotted" basis.

Note 2: Exhibitor registration includes one (1) full workshop registration covering food service, CD-ROM with full presentations, abstracts, and attendance at the workshop presentations. Additional exhibitors at the booth who wish to receive all conference privileges except the CD-ROM will be required to pay an additional \$50 registration fee.

Note 3: Materials shipped by vendors is stored free of charge Nov 12 through Nov 14. Additional storage will be charged at \$20 per day if shipped materials arrive sooner than Nov 12. If materials must be stored over the weekend, the \$40 weekend storage fee will apply.

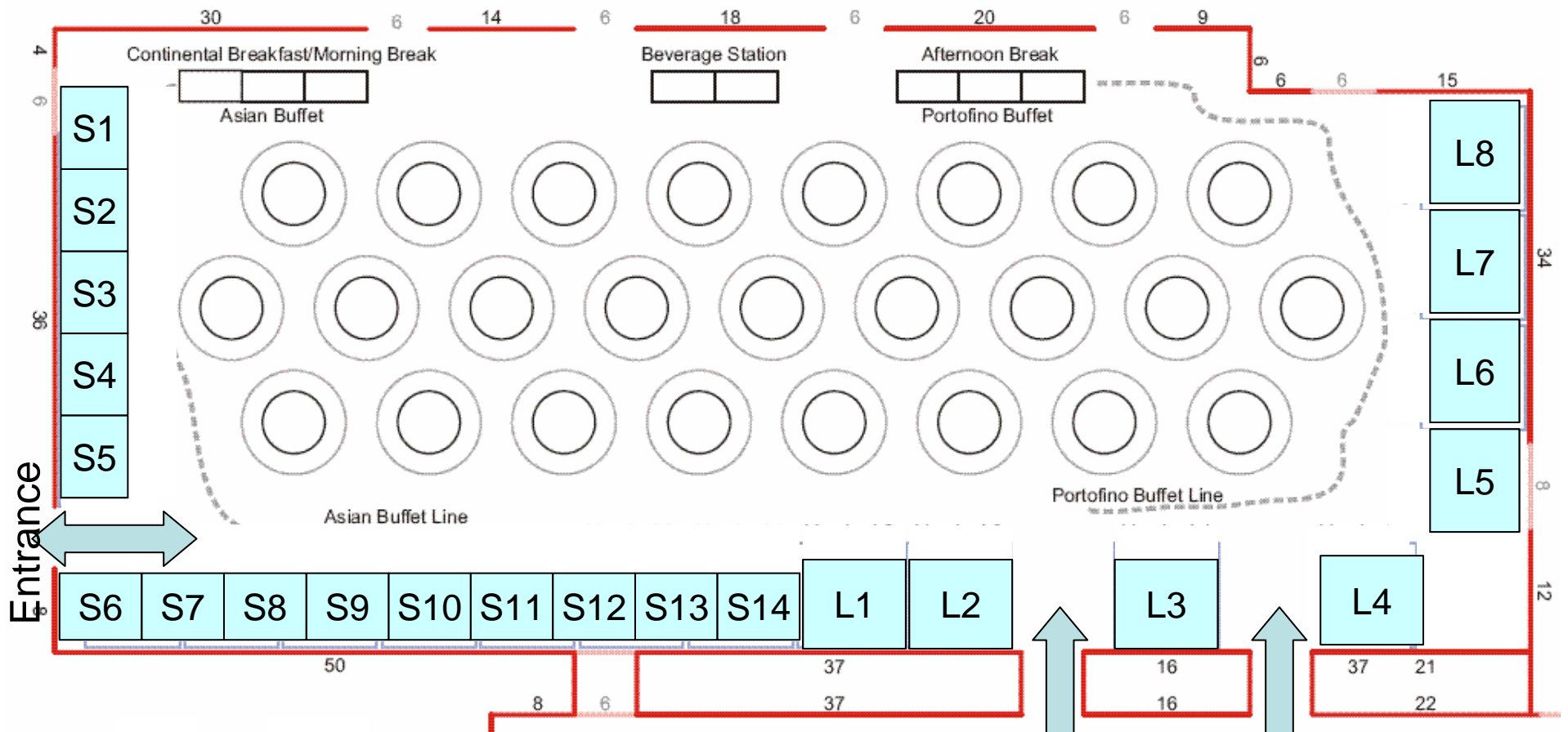
Check payable to "IEEE/CPMT Phoenix Chapter" for \$_____ is enclosed for booth fee. Please mail application along with check to: Mr. Surinder K. Tuli, Intel Corporation, Mail Stop: CH5-227, 5000 W Chandler Blvd, Chandler- AZ 85260; surinder.k.tuli@intel.com.

The undersigned on behalf of the organization or firm named above acknowledges this application to exhibit and, if this application is cancelled, agrees to pay a cancellation fee of 50% of the total booth cost. Upon approval, a copy of this application will be returned by fax to the exhibitor.

Exhibitor Representative _____ (Signature) _____ (Date)

Exhibition Contacts:
Mr. Steve Rockwell, Motorola Inc., M/S: EL375, 2100 E. Elliot Rd, Tempe, AZ 85284, Tel: 480-413-5235, Email: Steve.rockwell@ieee.org
Dr. Rashaunda Henderson, The University of Texas at Dallas, 800 W. Campbell Rd., M/S EC33, Richardson, TX 75080, Email: rmhen@ieee.org

Important Dates: Application Due **on October 24th, 2008** Payment Due **on November 7th, 2008**



3'x6' tables at each booth

Presentation Room

This is a preliminary configuration that may change by the date of the workshop